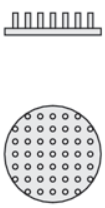
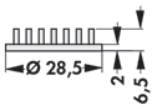
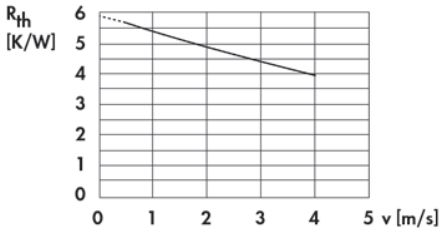
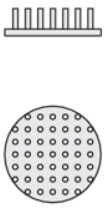
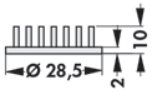
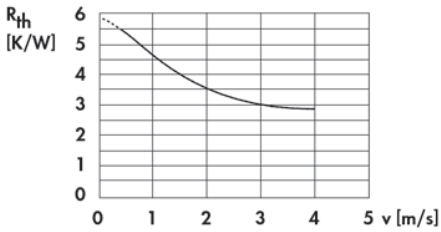
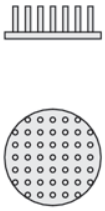
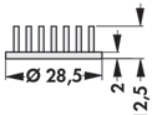
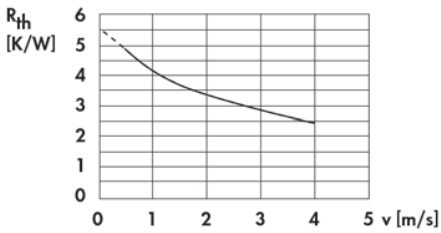
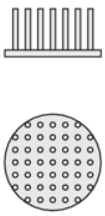
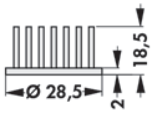
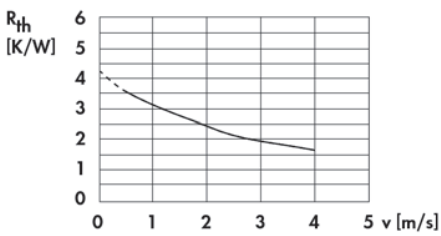
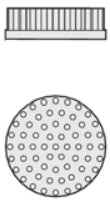
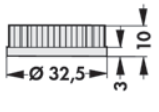
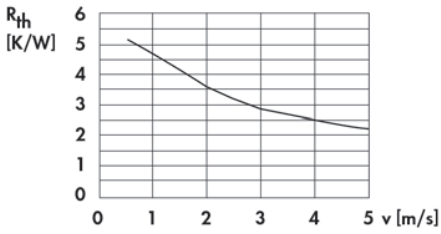
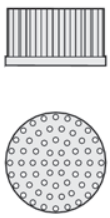
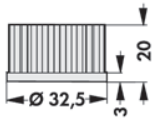
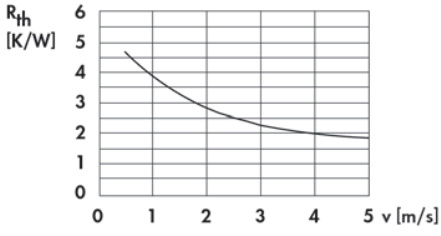
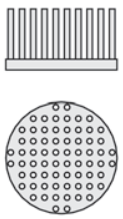
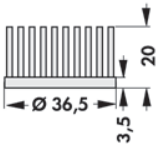
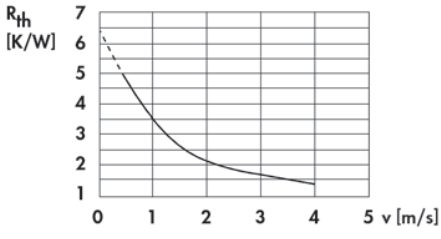
Pin heatsinks

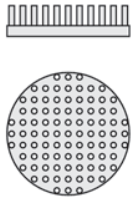
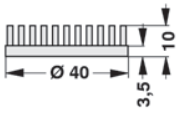
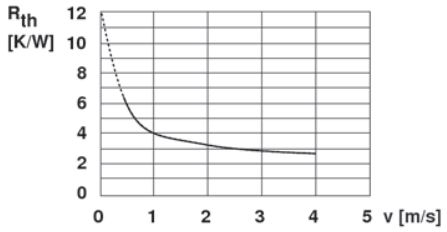
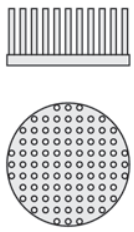
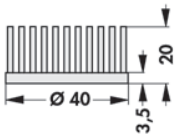
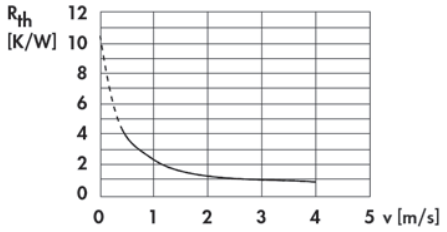
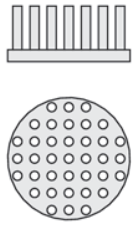
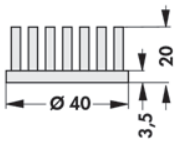
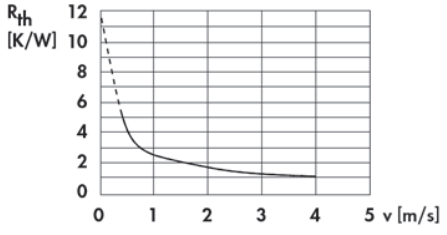
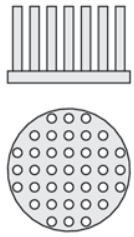
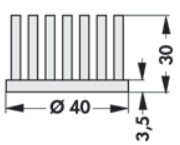
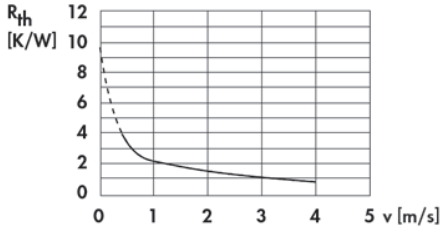
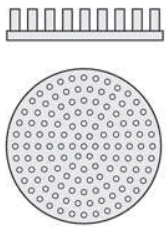
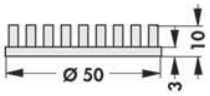
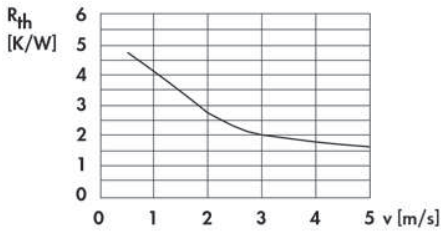
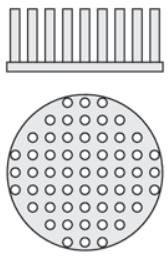
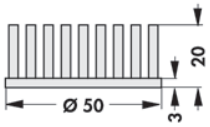
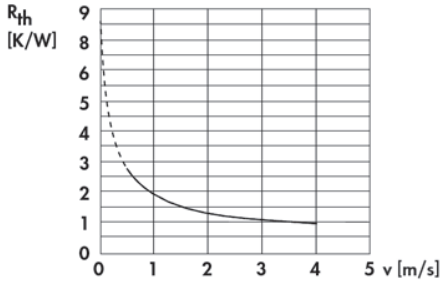
Round

art. no.			
ICK S R 28,5 x 6,5 WLF ... D 28,5 weight: 4.41 g			
art. no.			
ICK S R 28,5 x 10 WLF ... D 28,5 weight: 5.16 g			
art. no.			
ICK S R 28,5 x 12,5 WLF ... D 28,5 weight: 5.7 g			
art. no.			
ICK S R 28,5 x 18,5 WLF ... D 28,5 weight: 6.98 g			
art. no.			
ICK S R 32,5 x 10 WLF ... D 32 weight: 9.7 g			
art. no.			
ICK S R 32,5 x 20 WLF ... D 32 weight: 13.8 g			
art. no.			
ICK S R 36,5 x 20 WLF ... D 36,5 weight: 17.59 g			

Thermal conductive glue → **E 15**
Thermal conductive paste → **E 13**
SMD-heatsinks → **B 38 – 40**
Thermal conduct. foil WLFT 404/405 → **E 5**
Mounting material for semiconduct. → **E 37 – 41**
Thermal conduct. foil WLFT 404/405 → **E 5**
Hole pattern → **A 21**
Technical introduction → **A 2 - 7**

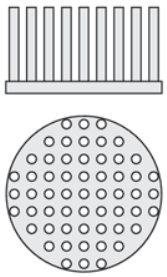
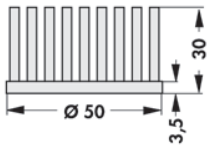
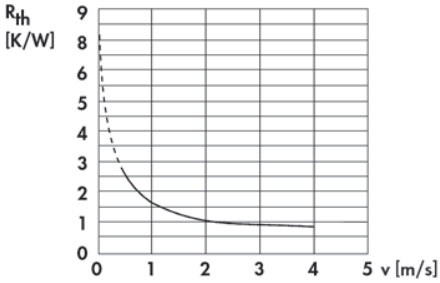
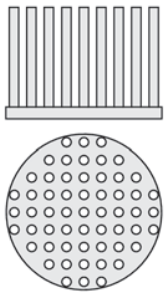
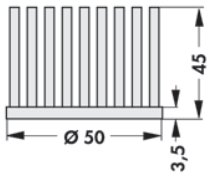
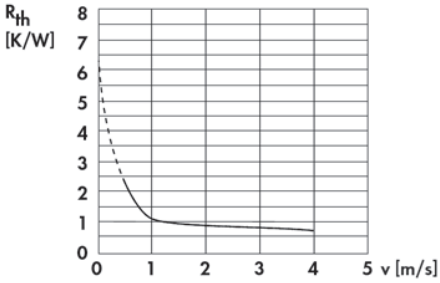
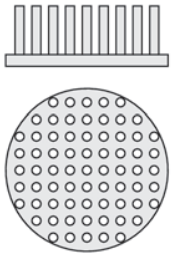
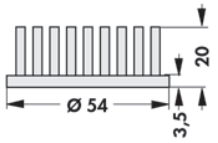
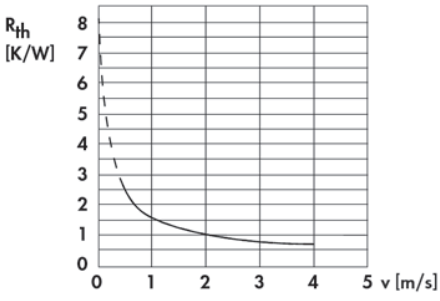
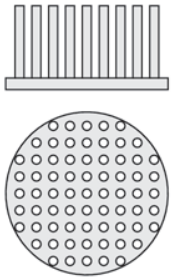
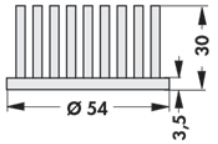
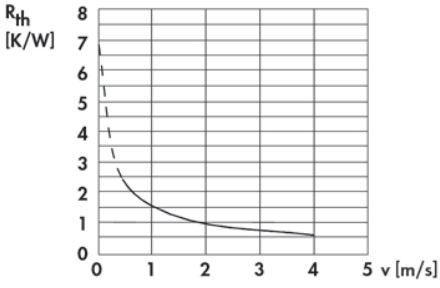
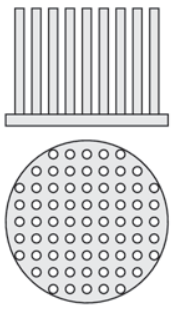
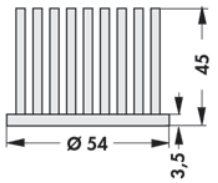
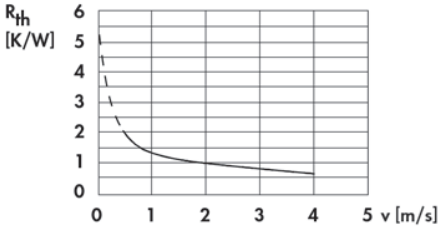
fischer elektronik

Pin heatsinks

art. no.			
ICK S R 40 x 10 WLF ... D 40 weight: 15.85 g			
art. no.			
ICK S R 40 x 20 WLF ... D 40 weight: 21.96 g			
art. no.			
ICK S R A 40 x 20 WLF ... D 40 weight: 22.18 g			
art. no.			
ICK S R 40 x 30 WLF ... D 40 weight: 29.24 g			
art. no.			
ICK S R 50 x 10 WLF ... D 50 weight: 22 g			
art. no.			
ICK S R 50 x 20 WLF ... D 50 weight: 34.39 g			

Thermal conductive glue → **E 15**
Thermal conductive paste → **E 13**
SMD-heatsinks → **B 38 – 40**
Thermal conduct. foil WLFT 404/405 → **E 5**
Mounting material for semiconduct. → **E 37 – 41**
Thermal conduct. foil WLFT 404/405 → **E 5**
Hole pattern → **A 21**
Technical introduction → **A 2 - 7**

Pin heatsinks

art. no.			
ICK S R 50 x 30 WLF ... D 50 weight: 45.28 g			
art. no.			
ICK S R 50 x 45 WLF ... D 50 weight: 61.59 g			
art. no.			
ICK S R 54 x 20 WLF ... D 54 weight: 40.94 g			
art. no.			
ICK S R 54 x 30 WLF ... D 54 weight: 54.11 g			
art. no.			
ICK S R 54 x 45 WLF ... D 54 weight: 73.86 g			

Thermal conductive glue → **E 15**
Thermal conductive paste → **E 13**
SMD-heatsinks → **B 38 – 40**
Thermal conduct. foil WLFT 404/405 → **E 5**
Mounting material for semiconduct. → **E 37 – 41**
Thermal conduct. foil WLFT 404/405 → **E 5**
Hole pattern → **A 21**
Technical introduction → **A 2 - 7**